

CLAIMS

1. A method of peeling a semiconductor chip,  
comprising the steps of:

5                   peeling a semiconductor chip adhered to a  
tape from said tape by a peeling device including a  
plurality of annular contact members arranged one after  
another from the outside to the inside, wherein the  
plurality of annular contact members are operated so  
that the semiconductor chip is successively peeled off  
10 from the tape from an outer circumferential portion  
thereof toward a central portion thereof.

2. The method of peeling a semiconductor chip  
according to claim 1, wherein the plurality of annular  
contact members are simultaneously moved, and then, the  
15 outermost annular contact member in the plurality of  
annular contact members is stopped and the remaining  
annular contact members are further moved  
simultaneously.

3. A device for peeling a semiconductor chip  
20 adhered to a tape off from said tape, comprising:

                  a plurality of annular contact members  
arranged one after another from the outside to the  
inside; and

                  an operation device for operating the  
25 plurality of annular contact members so that the  
semiconductor chip is successively peeled, from the  
tape, from an outer circumferential portion thereof to a  
central portion thereof.

4. The device for peeling a semiconductor chip  
30 according to claim 3, wherein the operation device  
includes a cam for operating the plurality of annular  
contact members.

5. The device for peeling a semiconductor chip according to claim 3, further comprising a frame defining a vacuum chamber therein, a top plate arranged on said frame and having an opening, and a suction  
5 device arranged above said frame, said annular contact members being arranged in said frame.